

TLV5617A

2.7-V TO 5.5-V LOW-POWER DUAL 10-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

features

- Dual 10-Bit Voltage Output DAC
- Programmable Settling Time
 - 2.5 μ s in Fast Mode
 - 12 μ s in Slow Mode
- Compatible With TMS320 and SPI™ Serial Ports
- Differential Nonlinearity <0.2 LSB Typ
- Monotonic Over Temperature

applications

- Digital Servo Control Loops
- Digital Offset and Gain Adjustment
- Industrial Process Control
- Machine and Motion Control Devices
- Mass Storage Devices

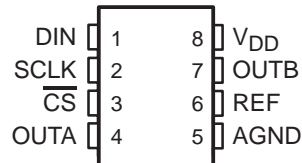
description

The TLV5617A is a dual 10-bit voltage output DAC with a flexible 3-wire serial interface. The serial interface is compatible with TMS320, SPI™, QSPI™, and Microwire™ serial ports. It is programmed with a 16-bit serial string containing 4 control and 10 data bits.

The resistor string output voltage is buffered by an x2 gain rail-to-rail output buffer. The buffer features a Class-AB output stage to improve stability and reduce settling time. The programmable settling time of the DAC allows the designer to optimize speed versus power dissipation.

Implemented with a CMOS process, the device is designed for single supply operation from 2.7 V to 5.5 V. It is available in an 8-pin SOIC package in standard commercial and industrial temperature ranges.

D PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T_A	PACKAGE
	SOIC (D)
0°C to 70°C	TLV5617ACD
–40°C to 85°C	TLV5617AID



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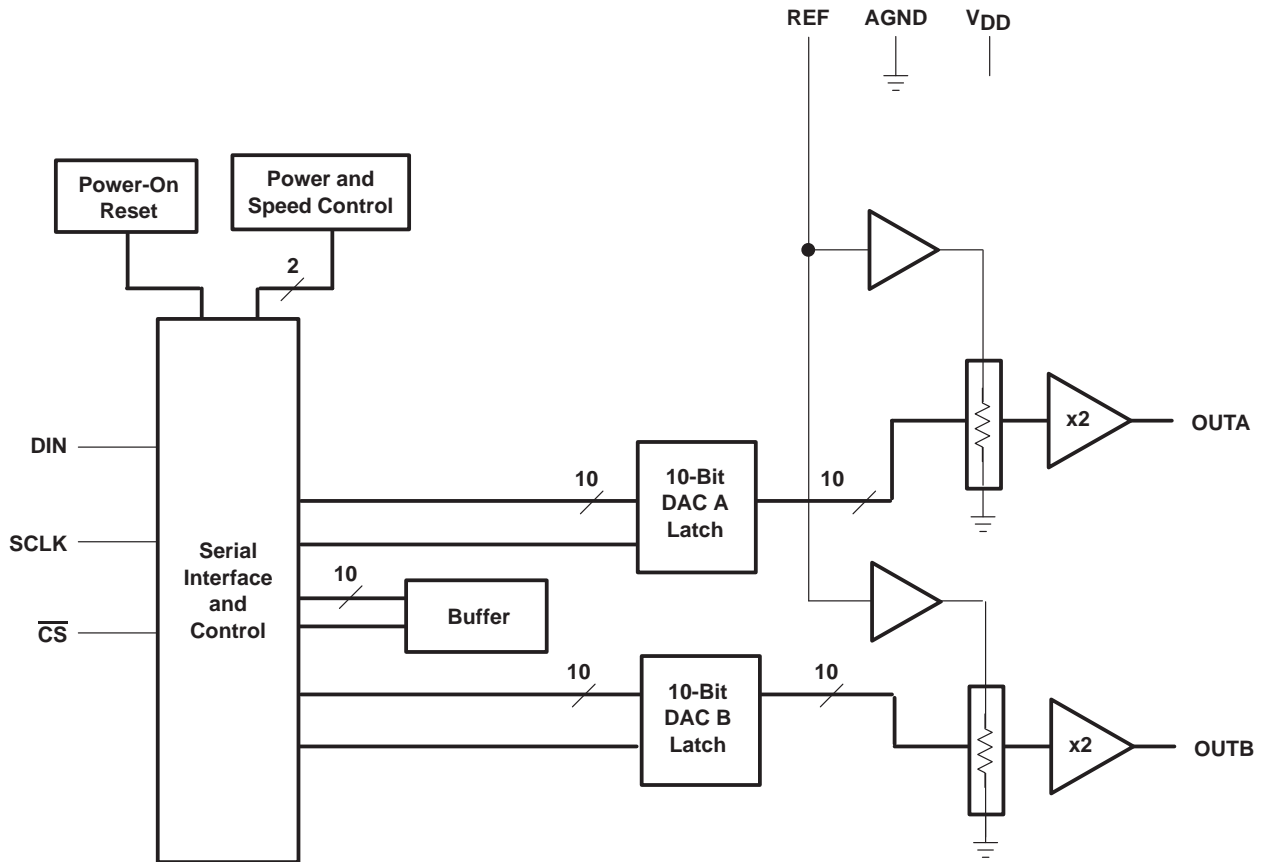
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SLAS234B – JULY 1999 – REVISED MARCH 2000

functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O/P	DESCRIPTION
AGND	5	P	Ground
$\overline{\text{CS}}$	3	I	Chip select. Digital input active low, used to enable/disable inputs.
DIN	1	I	Digital serial data input
OUTA	4	O	DAC A analog voltage output
OUTB	7	O	DAC B analog voltage output
REF	6	I	Analog reference voltage input
SCLK	2	I	Digital serial clock input
VDD	8	P	Positive power supply

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2.7-V TO 5.5-V LOW-POWER DUAL 10-BIT DIGITAL-TO-ANALOG
CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (V_{DD} to AGND)	7 V
Reference input voltage range	– 0.3 V to $V_{DD} + 0.3$ V
Digital input voltage range	– 0.3 V to $V_{DD} + 0.3$ V
Operating free-air temperature range, T_A : TLV5617AC	0°C to 70°C
TLV5617AI	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	$V_{DD} = 5$ V	4.5	5	5.5	V
	$V_{DD} = 3$ V	2.7	3	3.3	
Power on reset, POR		0.55		2	V
High-level digital input voltage, V_{IH}	$V_{DD} = 2.7$ V to 5.5 V	2			V
Low-level digital input voltage, V_{IL}	$V_{DD} = 2.7$ V to 5.5 V			0.8	V
Reference voltage, V_{ref} to REF terminal	$V_{DD} = 5$ V (see Note 1)	AGND	2.048	$V_{DD} - 1.5$	V
Reference voltage, V_{ref} to REF terminal	$V_{DD} = 3$ V (see Note 1)	AGND	1.024	$V_{DD} - 1.5$	V
Load resistance, R_L		2			k Ω
Load capacitance, C_L				100	pF
Clock frequency, f_{CLK}				20	MHz
Operating free-air temperature, T_A	TLV5617AC	0		70	°C
	TLV5617AI	–40		85	

NOTE 1: Due to the x2 output buffer, a reference input voltage $\geq (V_{DD} - 0.4$ V)/2 causes clipping of the transfer function.



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SLAS234B – JULY 1999 – REVISED MARCH 2000

electrical characteristics over recommended operating conditions (unless otherwise noted)

power supply

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{DD}	Power supply current	No load, All inputs = AGND or V _{DD} , DAC latch = 0x800	Fast	1.7	2.5	mA
			Slow	0.7	1	
	Power down supply current			1		μA
PSRR	Power supply rejection ratio	Zero scale, See Note 2		-65		dB
		Full scale, See Note 3		-65		

NOTES: 2. Power supply rejection ratio at zero scale is measured by varying V_{DD} and is given by:

$$PSRR = 20 \log [(E_{ZS}(V_{DDmax}) - E_{ZS}(V_{DDmin})/V_{DDmax}]$$

3. Power supply rejection ratio at full scale is measured by varying V_{DD} and is given by:

$$PSRR = 20 \log [(E_G(V_{DDmax}) - E_G(V_{DDmin})/V_{DDmax}]$$

static DAC specifications

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Resolution		10			bits
INL	Integral nonlinearity	See Note 4		±0.7	±1	LSB
DNL	Differential nonlinearity	See Note 5		±0.1	±1	LSB
E _{ZS}	Zero-scale error (offset error at zero scale)	See Note 6			±12	mV
E _{ZS TC}	Zero-scale-error temperature coefficient	See Note 7		10		ppm/°C
E _G	Gain error	See Note 8			±0.6	% full scale V
E _{G TC}	Gain-error temperature coefficient	See Note 9		10		ppm/°C

NOTES: 4. The relative accuracy of integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale, excluding the effects of zero-code and full-scale errors.

5. The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1-LSB amplitude change of any two adjacent codes.

6. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.

7. Zero-scale-error temperature coefficient is given by: $E_{ZS TC} = [E_{ZS}(T_{max}) - E_{ZS}(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.

8. Gain error is the deviation from the ideal output ($2V_{ref} - 1$ LSB) with an output load of 10 kΩ.

9. Gain temperature coefficient is given by: $E_{G TC} = [E_G(T_{max}) - E_G(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.

output specifications

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _O	Output voltage range	R _L = 10 kΩ			V _{DD} -0.4	V
	Output load regulation accuracy	V _O = 4.096 V, 2.048 V R _L = 2 kΩ			±0.29	% FS

reference input

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _I	Input voltage range		0		V _{DD} -1.5	V
R _I	Input resistance			10		MΩ
C _I	Input capacitance			5		pF
Reference input bandwidth	REF = 0.2 V _{pp} + 1.024 V dc	Fast		1.3		MHz
		Slow		525		kHz
Reference feedthrough	REF = 1 V _{pp} at 1 kHz + 1.024 V dc (see Note 10)			-80		dB

NOTE 10: Reference feedthrough is measured at the DAC output with an input code = 0x000.



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 CONVERTER WITH POWER DOWN**

SLAS234B – JULY 1999 – REVISED MARCH 2000

**electrical characteristics over recommended operating conditions (unless otherwise noted)
 (Continued)**

digital inputs

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = V_{DD}$			1	μA
I_{IL}	Low-level digital input current	$V_I = 0 V$	-1			μA
C_i	Input capacitance			8		pF

analog output dynamic performance

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{s(FS)}$	Output settling time, full scale	$R_L = 10 k\Omega$, See Note 11	$C_L = 100 pF$,	Fast	2.5		μs
				Slow	12		
$t_{s(CC)}$	Output settling time, code to code	$R_L = 10 k\Omega$, See Note 12	$C_L = 100 pF$,	Fast	1		μs
				Slow	2		
SR	Slew rate	$R_L = 10 k\Omega$, See Note 13	$C_L = 100 pF$,	Fast	3		V/ μs
				Slow	0.5		
Glitch energy		$\overline{DIN} = 0$ to 1, $\overline{CS} = V_{DD}$	FCLK = 100 kHz,		5		nV-s
SNR	Signal-to-noise ratio	$f_s = 102 kSPS$, $f_{out} = 1 kHz$, $R_L = 10 k\Omega$, $C_L = 100 pF$			56		dB
SINAD	Signal-to-noise + distortion				55		
THD	Total harmonic distortion				-62		
SFDR	Spurious free dynamic range				64		

- NOTES: 11. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of 0x020 to 0xFDC and 0xFDC to 0x020 respectively. Not tested, assured by design.
 12. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of one count. Not tested, assured by design.
 13. Slew rate determines the time it takes for a change of the DAC output from 10% to 90% of full-scale voltage.

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CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

digital input timing requirements

	MIN	NOM	MAX	UNIT
$t_{su}(CS-CK)$ Setup time, \overline{CS} low before first negative SCLK edge	10			ns
$t_{su}(C16-CS)$ Setup time, 16 th negative SCLK edge before \overline{CS} rising edge	10			ns
t_{wH} SCLK pulse width high	25			ns
t_{wL} SCLK pulse width low	25			ns
$t_{su}(D)$ Setup time, data ready before SCLK falling edge	10			ns
$t_h(D)$ Hold time, data held valid after SCLK falling edge	5			ns

timing requirements

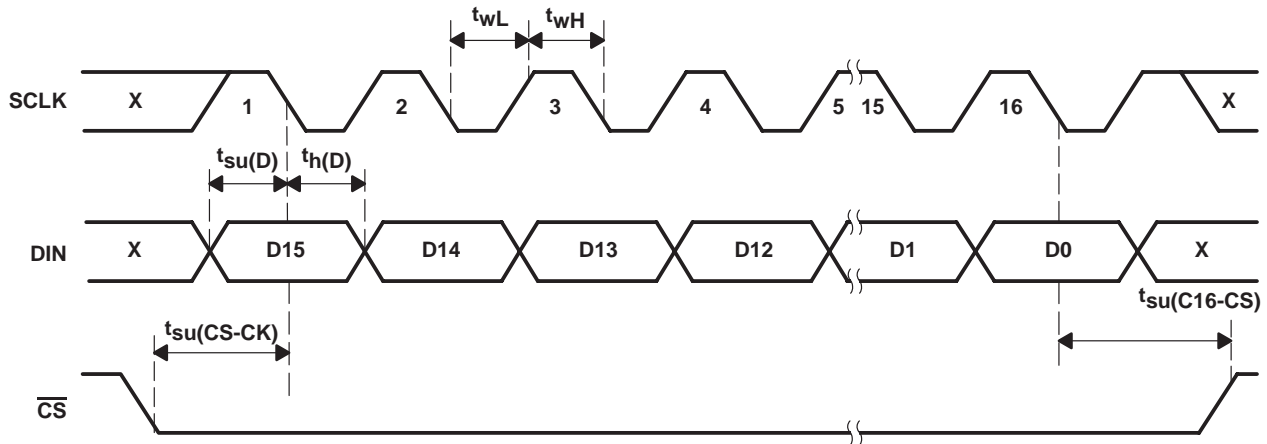


Figure 1. Timing Diagram

TLV5617A
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 CONVERTER WITH POWER DOWN**

SLAS234B – JULY 1999 – REVISED MARCH 2000

TYPICAL CHARACTERISTICS

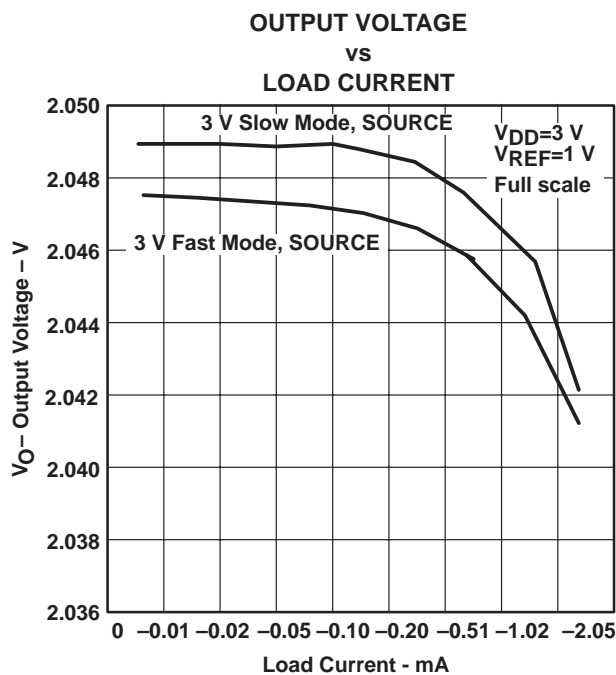


Figure 2

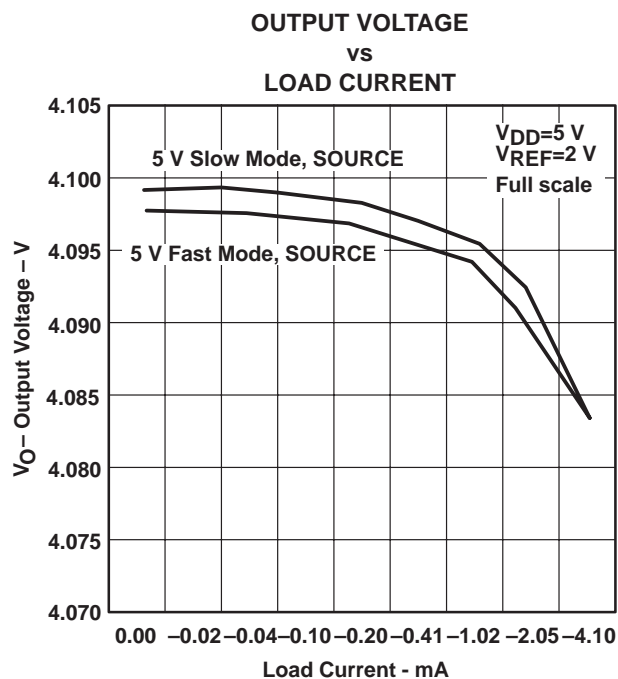


Figure 3

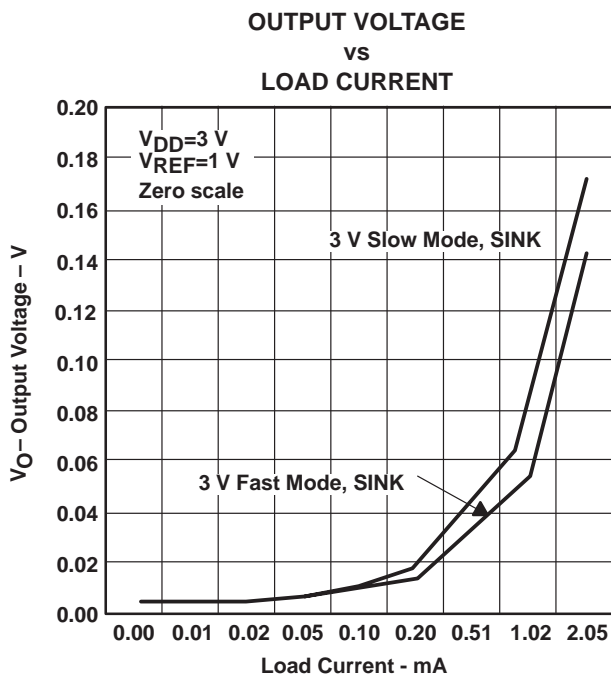


Figure 4

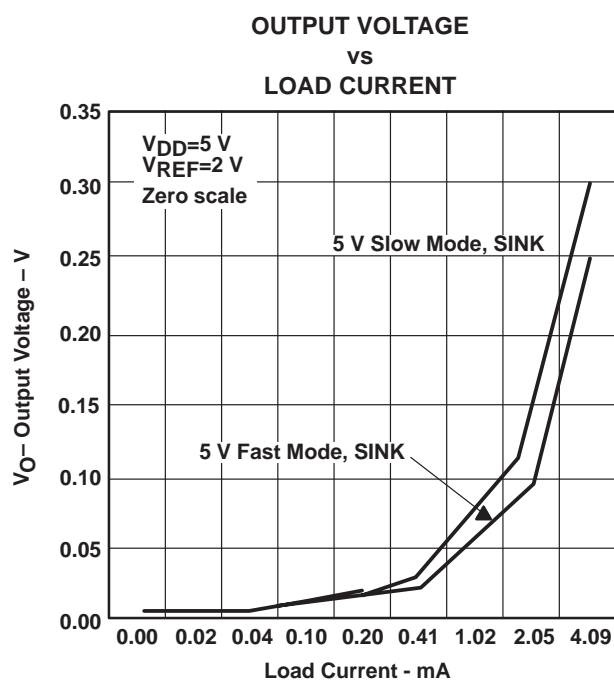


Figure 5

TLV5617A
2.7-V TO 5.5-V LOW-POWER DUAL 10-BIT DIGITAL-TO-ANALOG
CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE

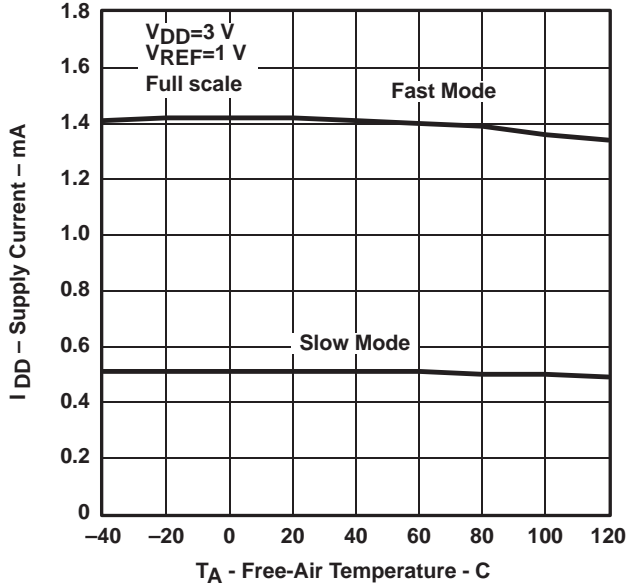


Figure 6

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE

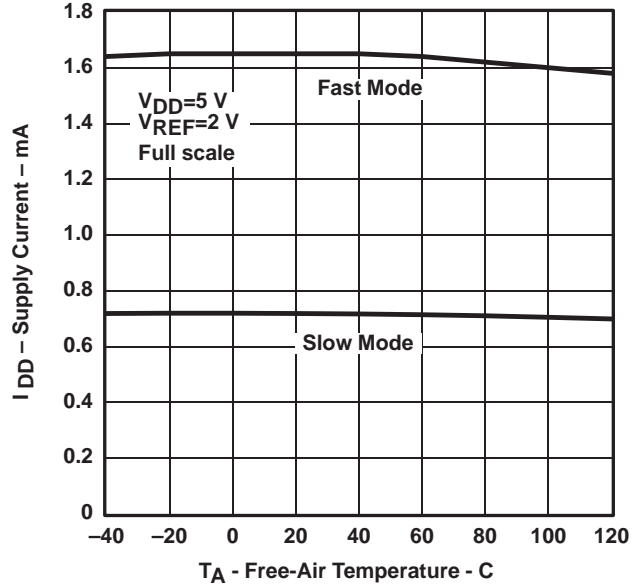


Figure 7

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

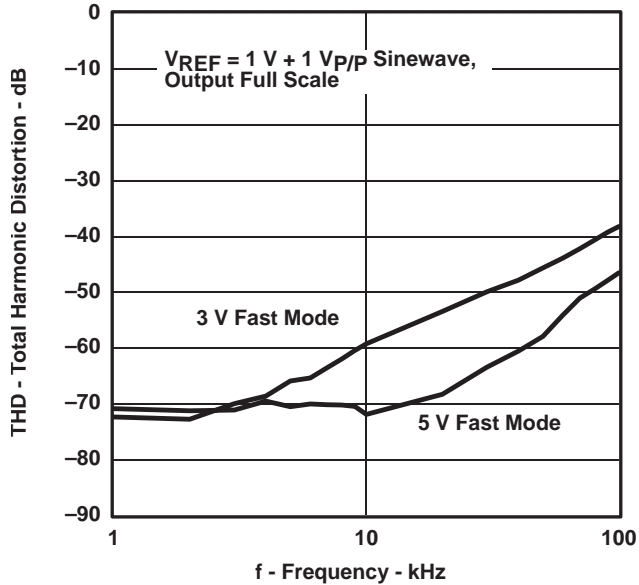


Figure 8

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

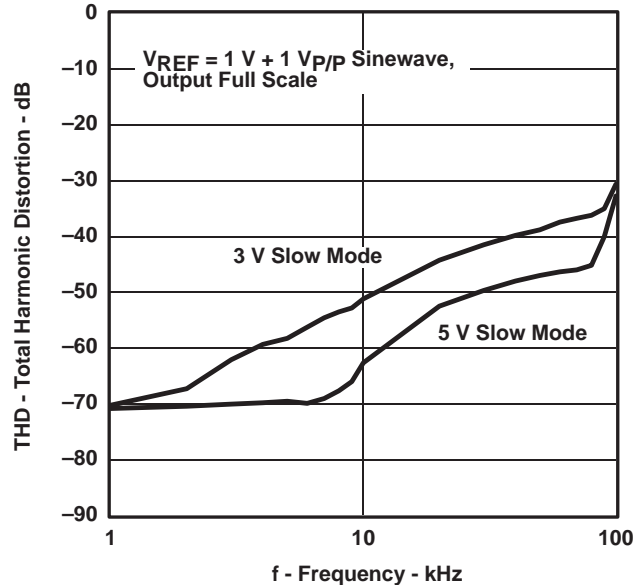


Figure 9



TYPICAL CHARACTERISTICS

INTEGRAL NONLINEARITY ERROR
VS
DIGITAL CODE

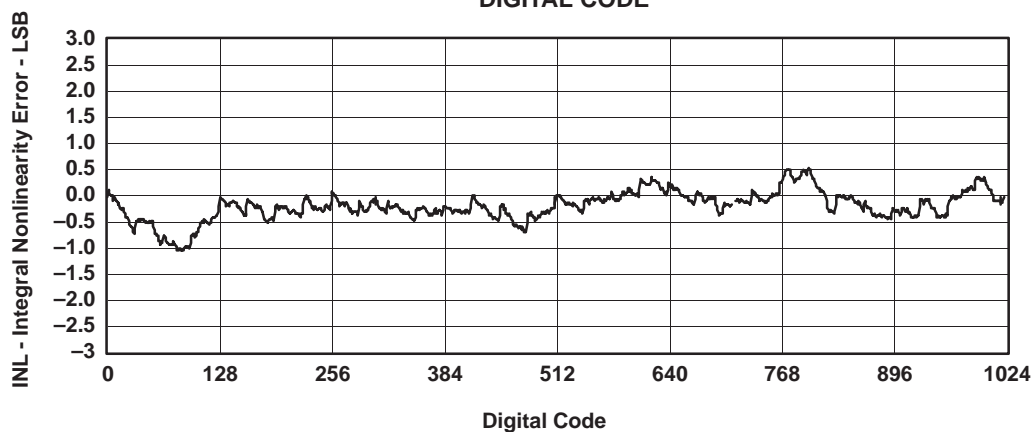


Figure 10

DIFFERENTIAL NONLINEARITY ERROR
VS
DIGITAL CODE

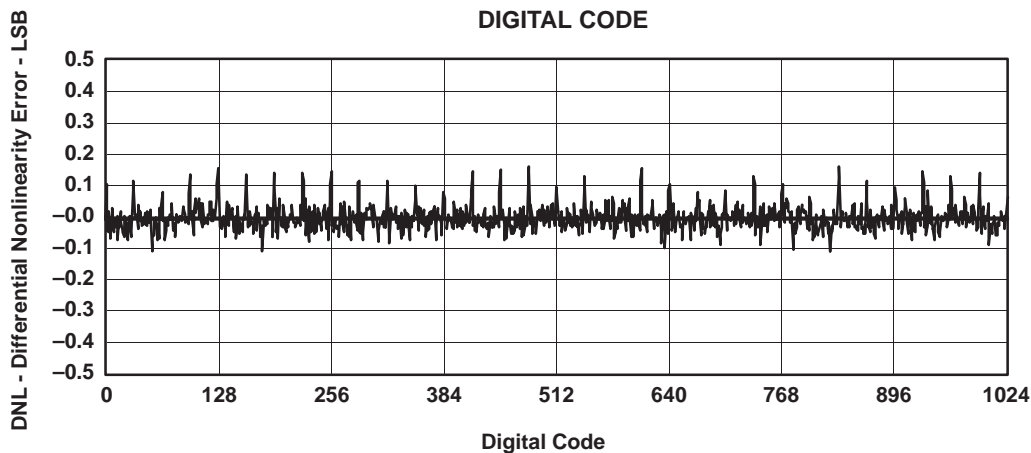


Figure 11

TLV5617A

2.7-V TO 5.5-V LOW-POWER DUAL 10-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

APPLICATION INFORMATION

general function

The TLV5617A is a dual 10-bit, single-supply DAC, based on a resistor-string architecture. It consists of a serial interface, a speed and power-down control logic, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by the reference) is given by:

$$2 \text{ REF} \frac{\text{CODE}}{0x1000} \text{ [V]}$$

Where REF is the reference voltage and CODE is the digital input value in the range 0x000 to 0xFFC. A power-on reset initially puts the internal latches to a defined state (all bits zero).

serial interface

A falling edge of $\overline{\text{CS}}$ starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or $\overline{\text{CS}}$ rises, the content of the shift register is moved to the target latches (DAC A, DAC B, BUFFER, CONTROL), depending on the control bits within the data word.

Figure 12 shows examples of how to connect the TLV5617A to TMS320, SPI™, and Microwire™.

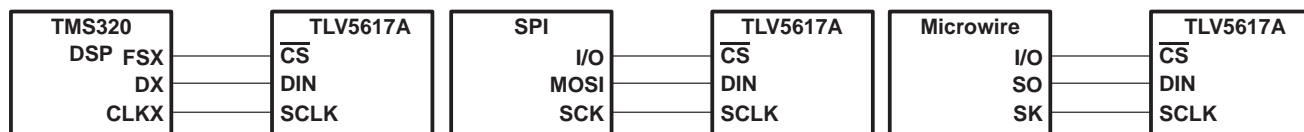


Figure 12. Three-Wire Interface

Notes on SPI™ and Microwire™: Before the controller starts the data transfer, the software has to generate a falling edge on the pin connected to $\overline{\text{CS}}$. If the word width is 8 bits (SPI™ and Microwire™) two write operations must be performed to program the TLV5617A. After the write operation(s), the holding registers or the control register are updated automatically on the 16th positive clock edge.

serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{\text{sclkmax}} = \frac{1}{t_{\text{whmin}} + t_{\text{wlmin}}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{\text{updatemax}} = \frac{1}{16 (t_{\text{whmin}} + t_{\text{wlmin}})} = 1.25 \text{ MHz}$$

Note that the maximum update rate is just a theoretical value for the serial interface, as the settling time of the TLV5617A should also be considered.

TLV5617A
2.7-V TO 5.5-V LOW-POWER DUAL 10-BIT DIGITAL-TO-ANALOG
CONVERTER WITH POWER DOWN

SLAS234B – JULY 1999 – REVISED MARCH 2000

APPLICATION INFORMATION

examples of operation (continued)

Both outputs are updated on the rising clock edge after D0 from the DAC A data word is sampled.

- Set powerdown mode:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
X	X	1	X	X	X	X	X	X	X	X	X	X	X	X	X

X = Don't care

linearity, offset, and gain error using single ended supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset, the output voltage may not change with the first code, depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage then remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 13.

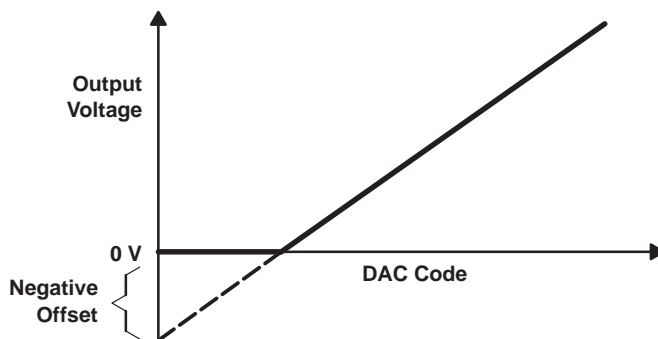


Figure 13. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero-input code (all inputs 0) and full-scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full-scale code and the lowest code that produces a positive output voltage.

definitions of specifications and terminology

integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.



definitions of specifications and terminology (continued)

zero-scale error (E_{ZS})

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

gain error (E_G)

Gain error is the error in slope of the DAC transfer function.

total harmonic distortion (THD)

THD is the ratio of the rms value of the first six harmonic components to the value of the fundamental signal. The value for THD is expressed in decibels.

signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

spurious free dynamic range (SFDR)

Spurious free dynamic range is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.

TLV5617A
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CONVERTER WITH POWER DOWN

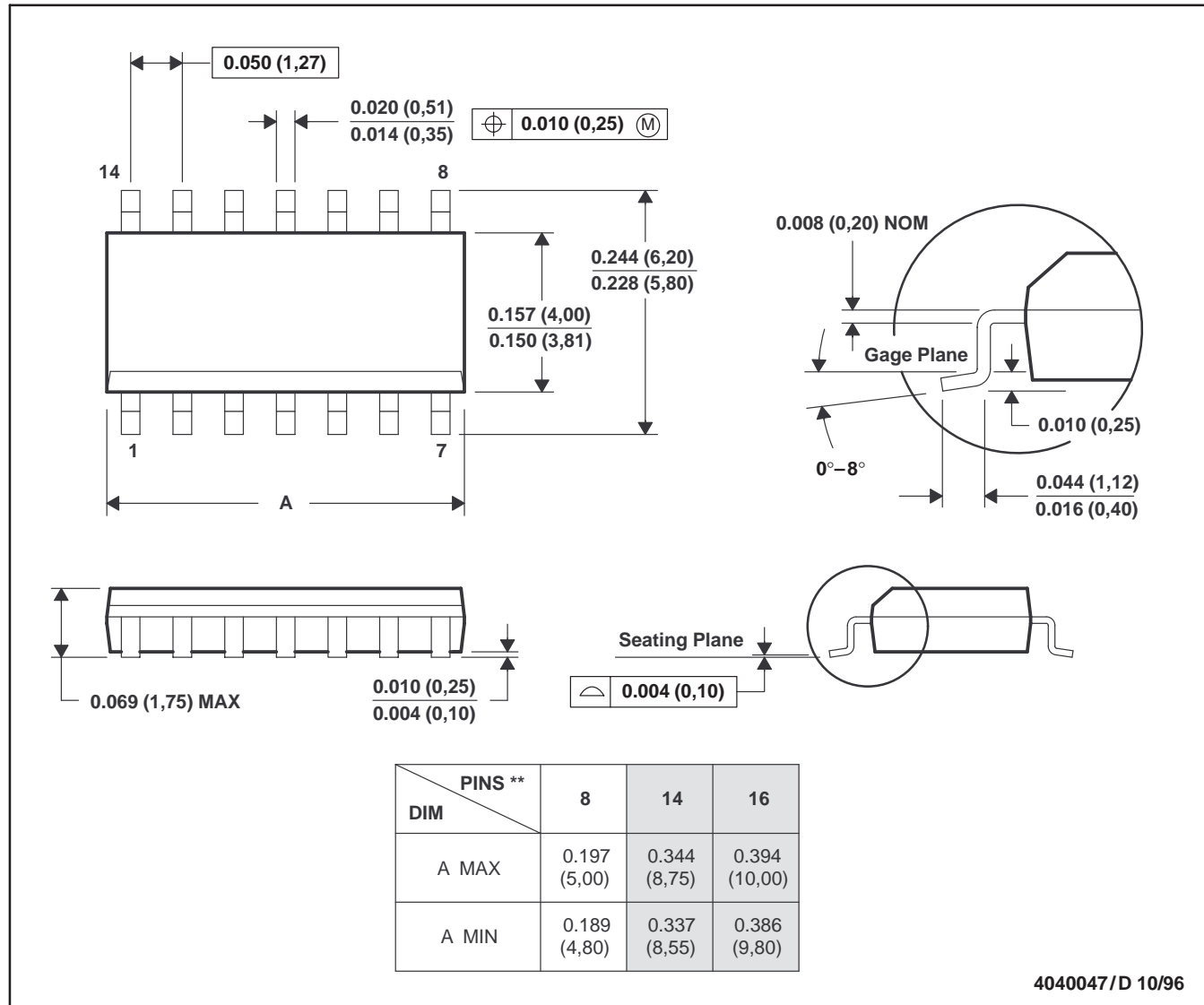
SLAS234B – JULY 1999 – REVISED MARCH 2000

MECHANICAL DATA

D (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

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